



Final Product Change Notification

201904001F01

Issue Date: 07-Apr-2019

Effective Date: 05-Jul-2019

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QUALITY

Change Category

- | | | | | |
|----------------------------------------------|---------------------------------------------|----------------------------------------------------|-----------------------------------------|--------------------------------------------------------------------|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input checked="" type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

33907 / 33908 and FS6407 / FS6408 Data Sheet Update Proposal: Modification of VCCA Output Voltage Foldback Threshold

Description of Change

NXP Semiconductors proposes data sheet updates for the Power System Basis Chip products associated with this notification, for parameter VCCA Output Voltage Foldback Threshold. In order to improve product performance, NXP proposes the following specification value updates:

VCCA Output Voltage Foldback Threshold:

- Increase Min value from 0.5 V to 0.6 V
- Increase Max value from 1.1 V to 1.2 V

The proposed new values have been evaluated versus applications conditions and are considered low risk. The attached presentation shows the specification extract associated with these parameters.

The new VCCA Output Voltage Foldback Threshold values will be incorporated in the next data sheet

specification revisions.

The current data sheet specification revisions are:

MC33907-MC33908D2 Rev 5.0

MC34FS6407-08 Rev 3.0

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-01.

Reason for Change

The proposed VCCA Output Voltage Foldback Threshold specification updates improve product performance:

- Current limit foldback is a reduction of the current limit in case of VCCA voltage is very low to limit the power dissipation.
- The foldback current limitation is activated only when $VCCA < VCCA_FB_TH$, which means in real life a VCCA short to GND.
- Proposed higher VCCA_FB_TH specification values are safer for the device since it reduces the current for a higher voltage value.

Identification of Affected Products

Product identification does not change.

Shipment of products tested with updated limits will occur upon PCN acceptance.

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 08-Jul-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Enhanced functionality associated with VCCA Output Voltage Foldback Threshold

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 07-May-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC33908NAE	935313228557	MC33908NAE	POWER SBC LIN	SOT1571-1	HLQFP48	RFS	Safety & Power Mgmt
MC33907NAE	935312441557	MC33907NAE	POWER SBC LIN	SOT1571-1	HLQFP48	RFS	Safety & Power Mgmt
MC33908LAE	935311339557	MC33908LAE	POWER SBC LIN	SOT1571-1	HLQFP48	RFS	Safety & Power Mgmt
MC33907LAE	935312346557	MC33907LAE	POWER SBC LIN	SOT1571-1	HLQFP48	RFS	Safety & Power Mgmt